Hi-performance No-clean Solder Paste

SE48-M955 & SS48-M955

■ Features

1) Employment of rigidly classified 20~45 micron solder powder ensures outstanding continual printability with fine pitch (0.5mm/20mil) and even super fine pitch (0.4mm/16mil) applications and long stencil idle time.

2) Carefully selected rosins and activators ensure powerful solder wetting.

3) Extremely long stencil idle time and tack time, offering a wide process window.

4) Low colour flux residue offers superior cosmetic appearance.

5) Conforms to Bellcore tests (Copper Mirror, Halides, Surface Insulation Resistance, Electromigration) GR-78-CORE, Issue 1.

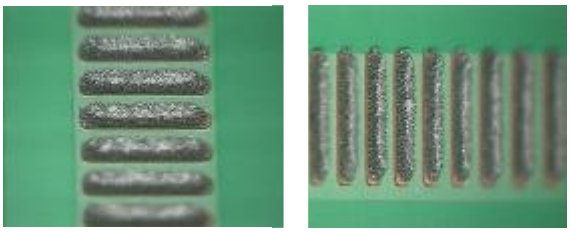
■ Specifications

Application			Printing - Stencil
Products			**SE48-M955 (SS48-M955)**
Alloy	Composition (%)		Sn63, Pb37 (Sn62, Pb36,Ag2)
	Shape		Spherical
	Particle size (μm)		20 - 45
Flux	Halide content (%)		0.0
	Surface insulation resistance *1	Initial value (Ω)	$> 1 \times 10^{12}$
		After humidification (Ω)	$> 1 \times 10^{11}$
	Aqueous solution resistivity*2 (Ω cm)		$> 5 \times 10^{4}$
	Flux type		ROL0
Product	Flux content (%)		10
	Viscosity*3 (Ps)		2,100
	Copper plate corrosion*4		Passed
	Solder spread factor (%)		90
	Tack time		> 36 hours
	Shelf life (below 10°C)		6 months

1. SIR ..... 40°C×90%RH×96Hr
2. Aqueous solution resistivity ..... In accordance with MIL specifications.
3. Viscosity ..... Malcom spiral type viscometer, PCU-205 at 25°C 10rpm
4. Copper plate corrosion ..... In accordance with JIS.

■ Printability – SE48-M955

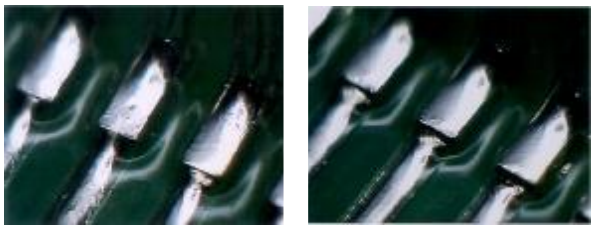
(Continual printing at 50mm/sec. stencil 150 m laser cut)



0.4mm pitch (30th print)

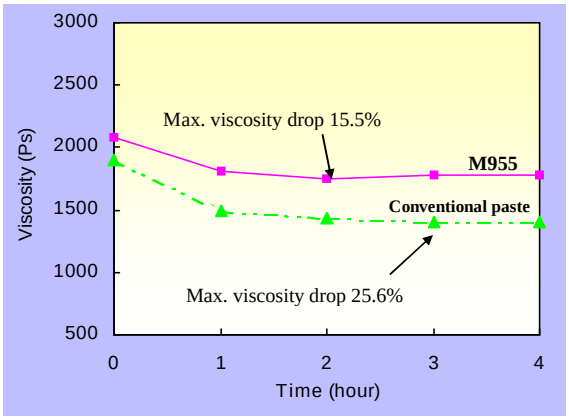
■ Solder wetting

(QFP 0.65mm pitch, Fe/Ni base alloy with Sn/Pb plated)

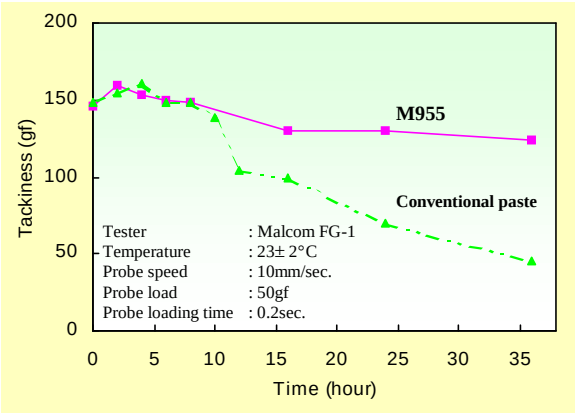


SE48-M955 Conventional solder paste

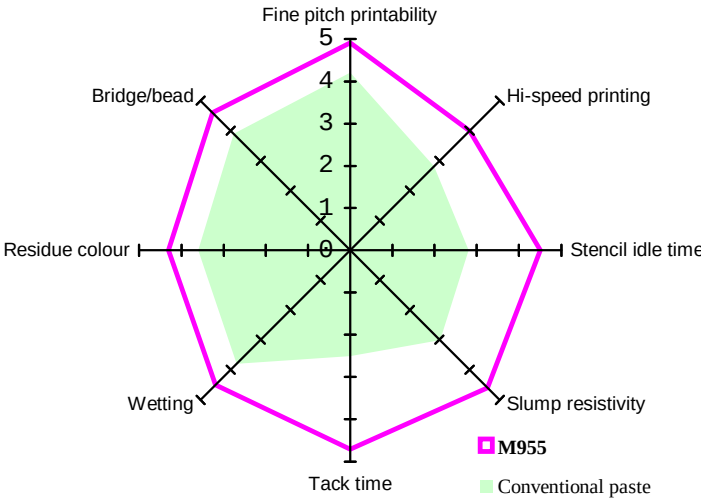
■ Viscosity variation in continual printing



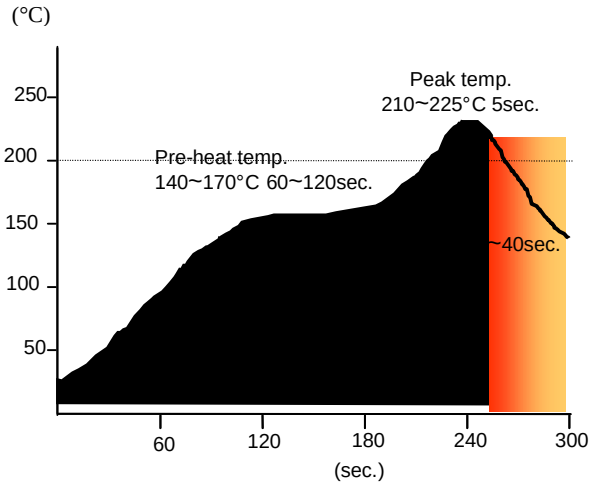
■ Tack force



■ Features comparison *(0: Bad → 5: Good)*



■ Recommended reflow profile



KOKI COMPANY LIMITED
32-1, Senju Asahi-cho, Adachi-ku, Tokyo 120-0026
Tel・(03) 5244-1521 Fax・(03) 5244-1527